ON Semiconductor®

Final Product/Process Change Notification

Document # : FPCN22203X
Issue Date: 12 July 2018

Title of Change:	ON Semiconductor is expanding assembly capacity via qualifying external package/assembly subcontractor. Applicable to the family of products (and related OPNs) NCP3230, NCP3231A, NCP3231, NCP3232N, NCP3233, NCP3235 and NCP5339. Ref: IPCN 22203X
Proposed first ship date:	19 October 2018 or earlier upon customer approval
Contact information:	Contact your local ON Semiconductor Sales Office or Joe Chong <Joe.Chong@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Paul Syndergaard <Paul.Syndergaard@onsemi.com>
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>
Change Part Identification:	Parts can be identified through date code marking following ON Semiconductor standards. Contact your local ON Semiconductor Sales Office for the specific date code information.
Change Category:	☐ Wafer Fab Change ☑ Assembly Change ☐ Test Change ☐ Other ____________

Change Sub-Category(s):

☑ Manufacturing Site Addition
☐ Manufacturing Site Transfer
☐ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: ______________________

Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: Advanced Semiconductor Engineering (ASE), Penang, Malaysia

Description and Purpose:

ON Semiconductor is expanding the subject products assembly capacity via addition of external assembly subcontractor in the supply chain.

There is no change to the datasheet specifications, or any other aspect of the product.

Reason: Assembly capacity expansion for the subject products.

Item to be changed:	Before Change Description	After Change Description
Addition of Product Assembly Site	ON Semiconductor, Seremban, Malaysia (Internal Assembly Facility)	After the change, Assembly will be done in two locations: 1. ON Semiconductor, Seremban, Malaysia 2. Advanced Semiconductor Engineering (ASE), Penang, Malaysia (subcontractor)

Reliability Data Summary:

QV DEVICE NAME NCP3231AMNTXG
NCP3235MNTXG
NCP5339MNTXTG
PACKAGE QFN 40 6*6

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/252
TC	JESD22-A104	Ta= - 65°C to +150°C	500 cyc	0/240
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C	Pre HAST/TC	0/ 1473
RSH	JESD22- B106	Ta = 265C, 10 sec		0/270
SAT	JSTD035	Scanning Acoustical Tomography	Delam check Pre/post PC	0/ 225
ED	ON Datasheet	Electrical Distribution	Compared to control lot	>1.67

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Part Number	Qualification Vehicle
NCP3230MNTXG	NCP3231AMNTXG NCP3235MNTXG NCP5339MNTXG
NCP3231MNTXG	
NCP3231AMNTXG	
NCP3232NMNTXG	
NCP3233MNTXG	
NCP5339MNTXG	
NCP3235MNTXG	